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Kind regards,

Team Nexperia



BC68PAS series

20 V, 2 A NPN medium power transistors

Rev. 1 — 19 June 2015

Product data sheet

1. Product profile

1.1 General description

NPN medium power transistors in an ultra thin DFN2020D-3 (SOT1061D) leadless small Surface-Mounted Device (SMD) plastic package with medium power capability and visible and solderable side pads.

PNP complement: BC69PAS series

1.2 Features and benefits

- High collector current capability
 I_C and I_{CM}
- Reduced Printed-Circuit Board (PCB) area requirements
- Exposed heat sink for excellent thermal and electrical conductivity
- AEC-Q101 qualified
- Two current gain selections
- Leadless very small SMD plastic package with medium power capability
- Suitable for Automatic Optical Inspection (AOI) of solder joint

1.3 Applications

- Linear voltage regulators
- Battery driven devices
- MOSFET drivers
- Low-side switches
- Power management
- Amplifiers

1.4 Quick reference data

Table 1. Quick reference data

$T_{amb} = 25\text{ °C}$ unless otherwise specified

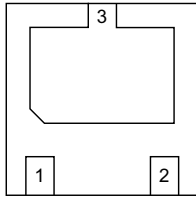
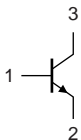
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{CEO}	collector-emitter voltage	open base	-	-	20	V
I_C	collector current		-	-	2	A
I_{CM}	peak collector current	single pulse; $t_p \leq 1\text{ ms}$	-	-	3	A
h_{FE}	DC current gain	$V_{CE} = 1\text{ V}$; $I_C = 500\text{ mA}$	[1]	85	-	375
	h_{FE} selection -25	$V_{CE} = 1\text{ V}$; $I_C = 500\text{ mA}$	[1]	160	-	375

[1] Pulse test: $t_p \leq 300\text{ }\mu\text{s}$; $\delta \leq 0.02$.



2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Graphic symbol
1	base	 <p>Transparent top view</p>	 <p>sym021</p>
2	emitter		
3	collector		

3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BC68PAS	DFN2020D-3	plastic thermal enhanced ultra thin small outline package; no leads; 3 terminals; body 2 × 2 × 0.65 mm.	SOT1061D
BC68-25PAS			

4. Marking

Table 4. Marking codes

Type number	Marking code
BC68PAS	BY
BC68-25PAS	BZ

5. Limiting values

Table 5. Limiting values

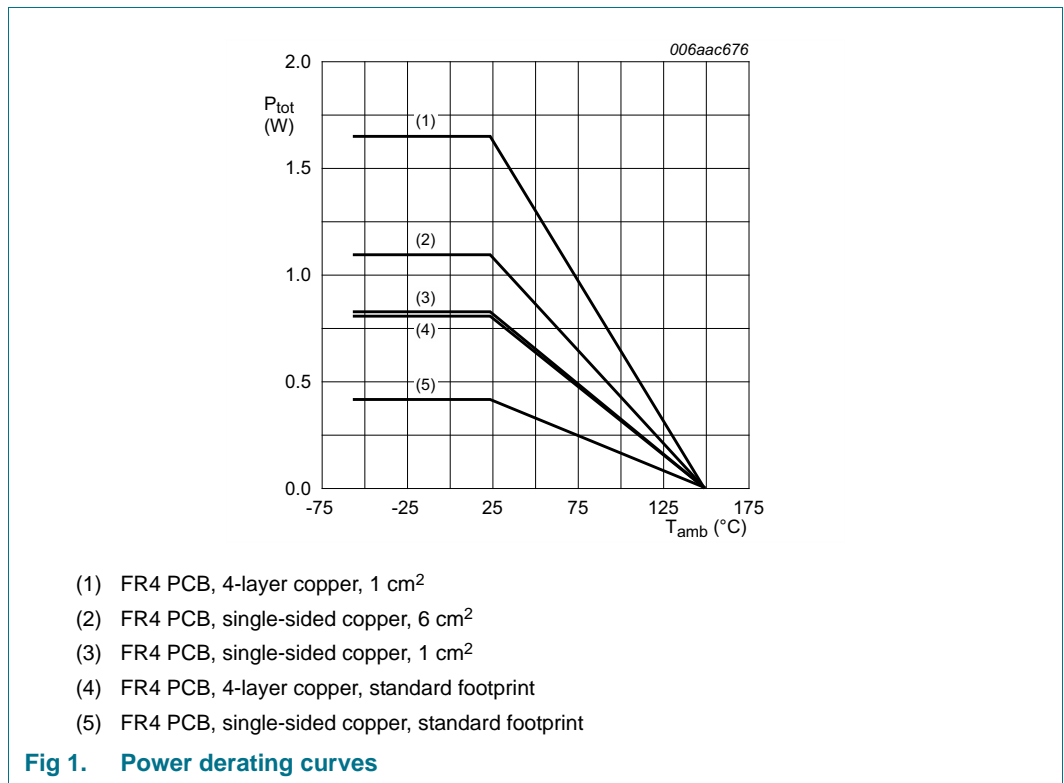
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CBO}	collector-base voltage	open emitter	-	32	V
V_{CEO}	collector-emitter voltage	open base	-	20	V
V_{EBO}	emitter-base voltage	open collector	-	5	V
I_C	collector current		-	2	A
I_{CM}	peak collector current	single pulse; $t_p \leq 1$ ms	-	3	A
I_B	base current		-	0.4	A

Table 5. Limiting values ...continued
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit	
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C	[1]	-	420	mW
			[2]	-	830	mW
			[3]	-	1.1	W
			[4]	-	810	mW
			[5]	-	1.65	W
T _j	junction temperature		-	150	°C	
T _{amb}	ambient temperature		-55	150	°C	
T _{stg}	storage temperature		-65	150	°C	

- [1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and mounting pad for collector 1 cm².
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated and mounting pad for collector 6 cm².
- [4] Device mounted on an FR4 PCB, 4-layer copper, tin-plated and standard footprint.
- [5] Device mounted on an FR4 PCB, 4-layer copper, tin-plated and mounting pad for collector 1 cm².

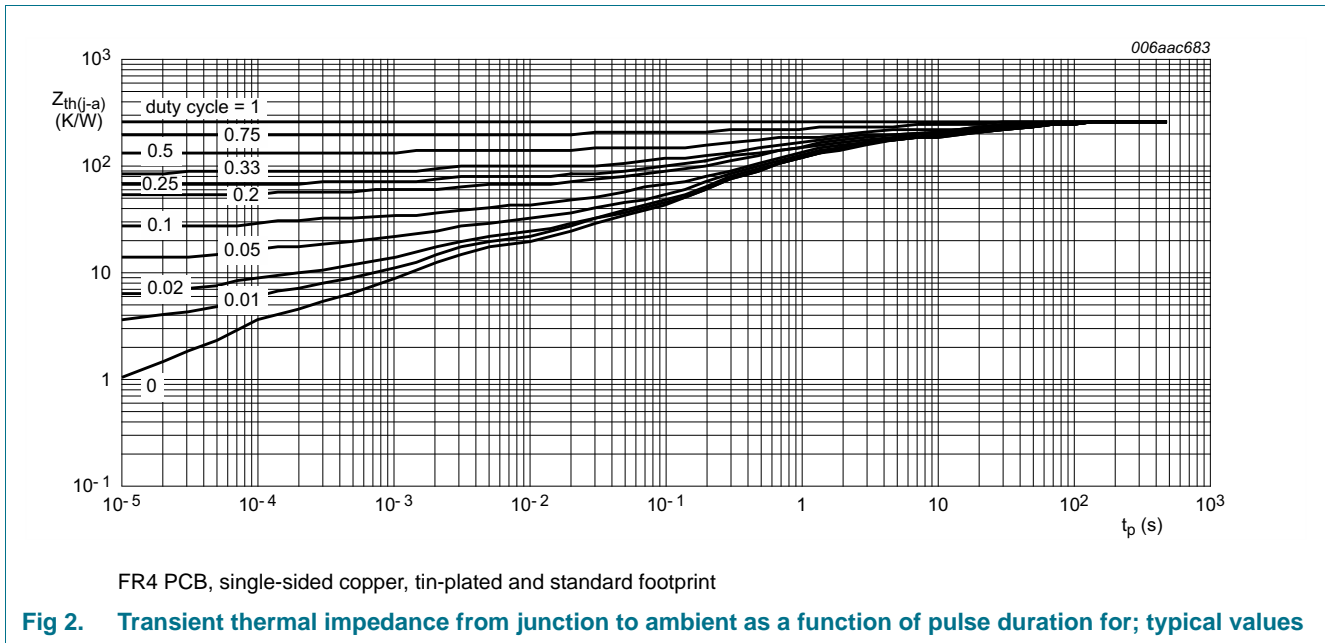


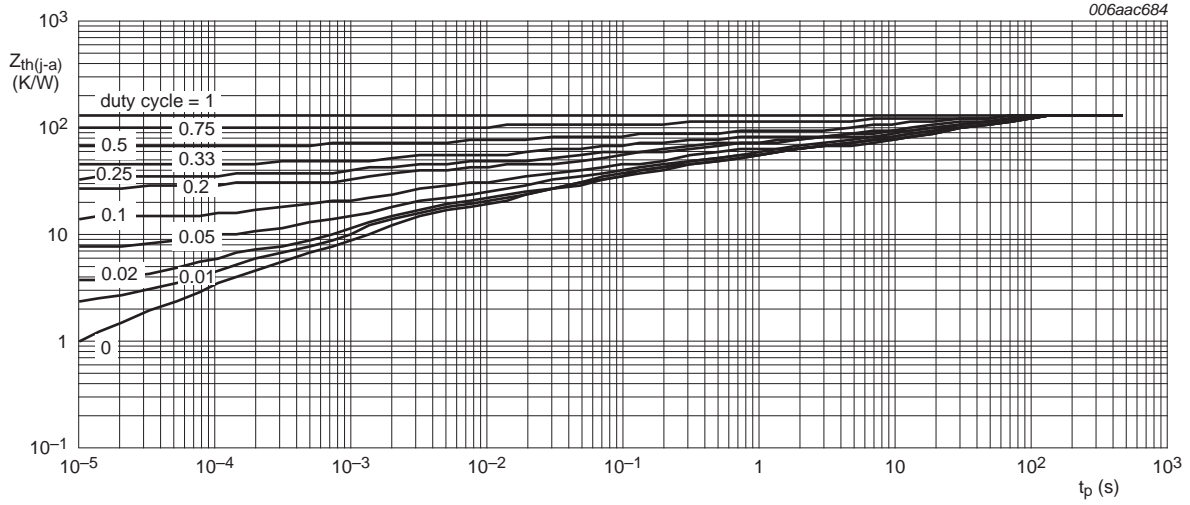
6. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1] 298	K/W
			[2] 151	K/W
			[3] 114	K/W
			[4] 154	K/W
			[5] 76	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point	in free air	20	K/W

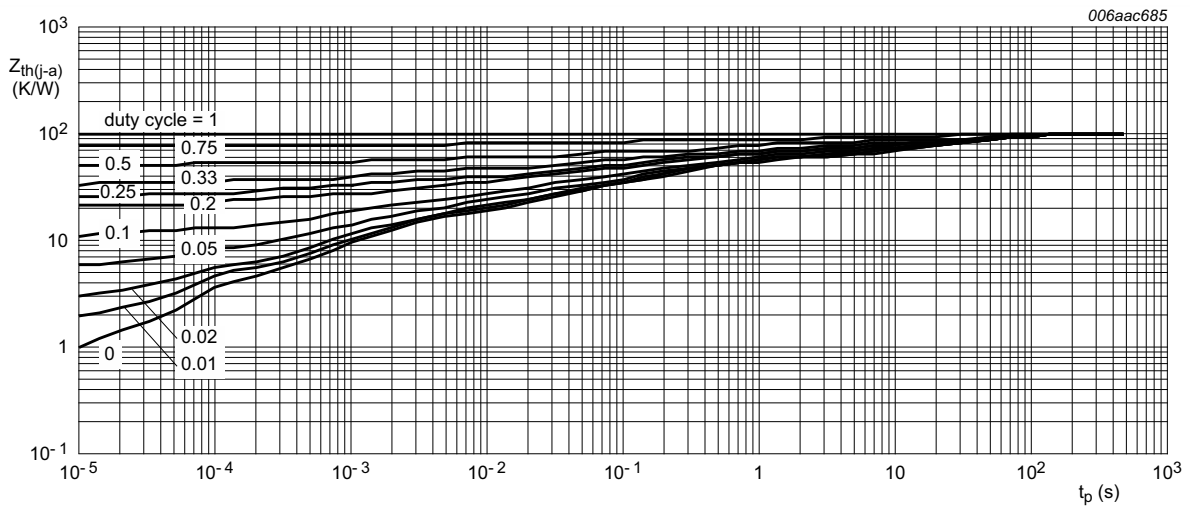
- [1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and mounting pad for collector 1 cm².
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated and mounting pad for collector 6 cm².
- [4] Device mounted on an FR4 PCB, 4-layer copper, tin-plated and standard footprint.
- [5] Device mounted on an FR4 PCB, 4-layer copper, tin-plated and mounting pad for collector 1 cm².





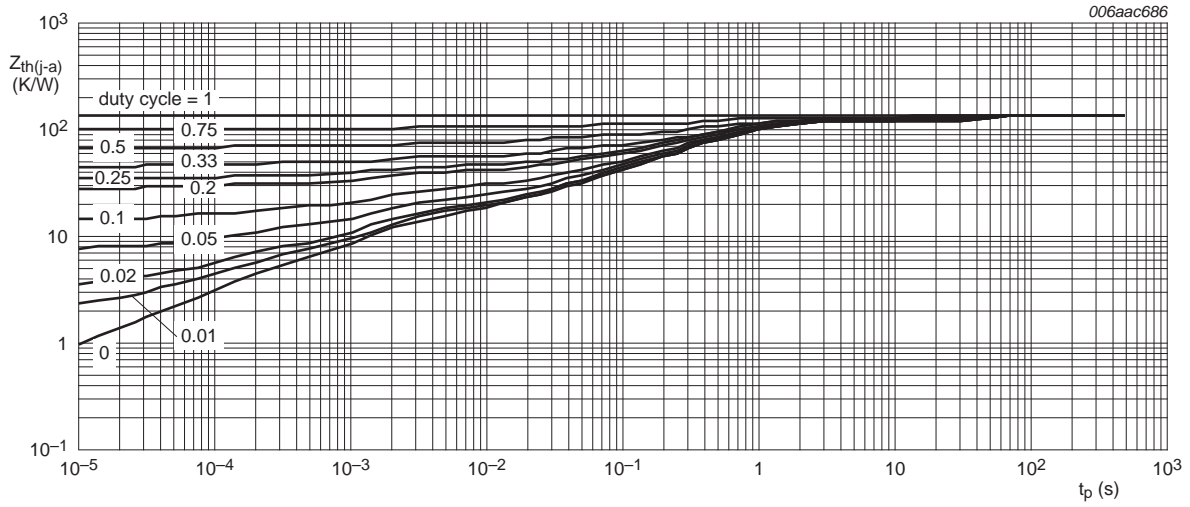
FR4 PCB, single-sided copper, tin-plated and mounting pad for collector 1 cm^2

Fig 3. Transient thermal impedance from junction to ambient as a function of pulse duration for; typical values



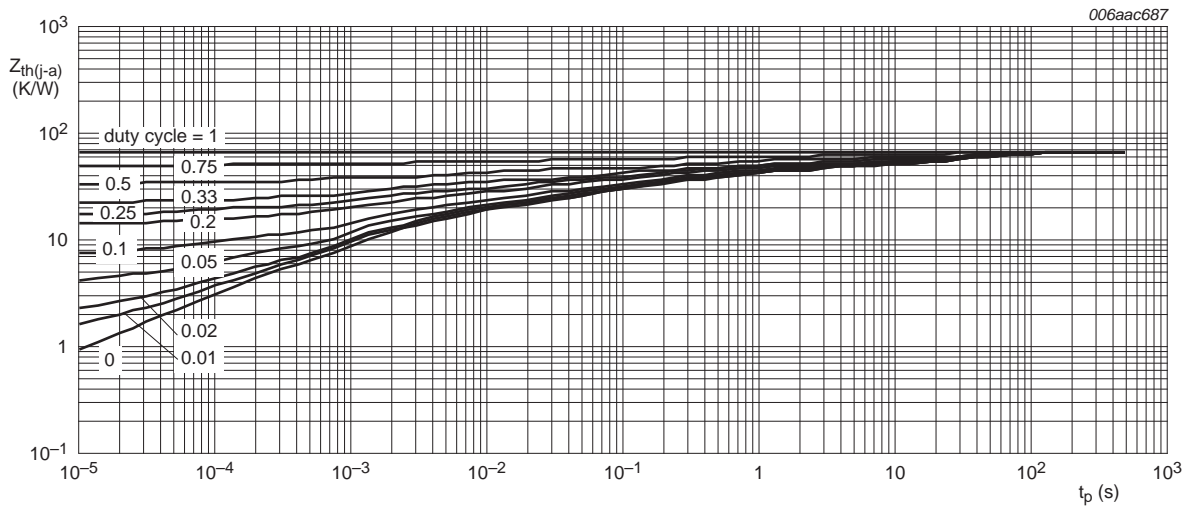
FR4 PCB, single-sided copper, tin-plated and mounting pad for collector 6 cm^2

Fig 4. Transient thermal impedance from junction to ambient as a function of pulse duration for; typical values



FR4 PCB, 4-layer copper, tin-plated and standard footprint

Fig 5. Transient thermal impedance from junction to ambient as a function of pulse duration for; typical values



FR4 PCB, 4-layer copper, tin-plated and mounting pad for collector 1 cm²

Fig 6. Transient thermal impedance from junction to ambient as a function of pulse duration for; typical values

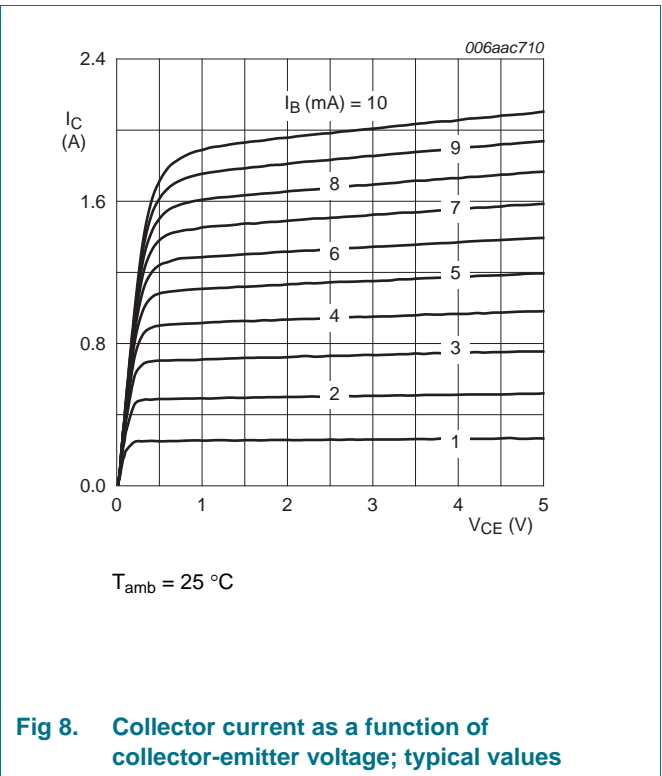
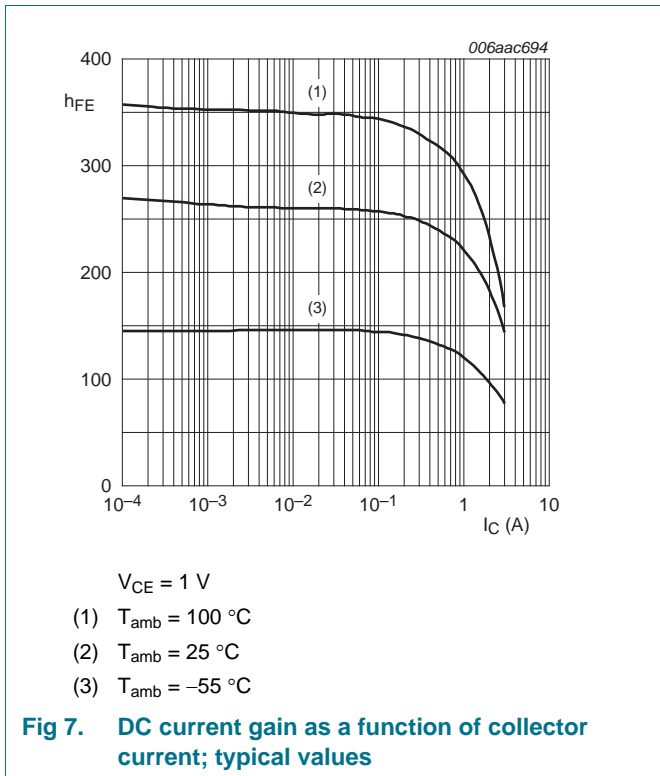
7. Characteristics

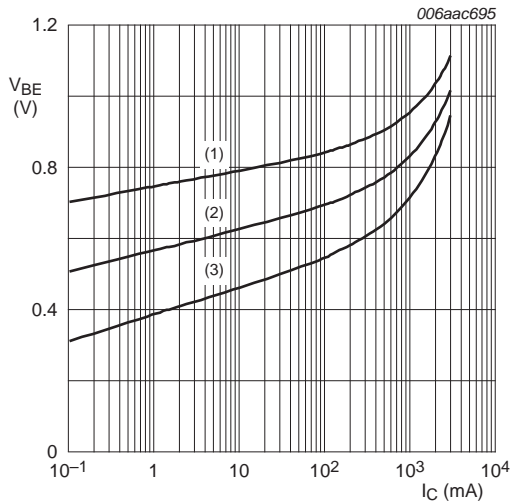
Table 7. Characteristics

$T_{amb} = 25\text{ }^{\circ}\text{C}$ unless otherwise specified

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I_{CBO}	collector-base cut-off current	$V_{CB} = 25\text{ V}; I_E = 0\text{ A}$	-	-	100	nA
		$V_{CB} = 25\text{ V}; I_E = 0\text{ A}; T_j = 150\text{ }^{\circ}\text{C}$	-	-	10	μA
I_{EBO}	emitter-base cut-off current	$V_{EB} = 5\text{ V}; I_C = 0\text{ A}$	-	-	100	nA
h_{FE}	DC current gain	$V_{CE} = 10\text{ V}; I_C = 5\text{ mA}$	50	-	-	
		$V_{CE} = 1\text{ V}; I_C = 500\text{ mA}$	[1]	85	-	375
		$V_{CE} = 1\text{ V}; I_C = 1\text{ A}$	[1]	60	-	-
		$V_{CE} = 1\text{ V}; I_C = 2\text{ A}$	[1]	40	-	-
	h_{FE} selection -25	$V_{CE} = 1\text{ V}; I_C = 500\text{ mA}$	[1]	160	-	375
V_{CEsat}	collector-emitter saturation voltage	$I_C = 1\text{ A}; I_B = 100\text{ mA}$	[1]	-	0.5	V
		$I_C = 2\text{ A}; I_B = 200\text{ mA}$	[1]	-	0.6	V
V_{BE}	base-emitter voltage	$I_C = 5\text{ mA}; V_{CE} = 10\text{ V}$	[1]	-	0.7	V
		$I_C = 1\text{ A}; V_{CE} = 1\text{ V}$	[1]	-	1	V
f_T	transition frequency	$V_{CE} = 5\text{ V}; I_C = 50\text{ mA}; f = 100\text{ MHz}$	40	170	-	MHz
C_c	collector capacitance	$V_{CB} = 10\text{ V}; I_E = i_e = 0\text{ A}; f = 1\text{ MHz}$	-	22	-	pF

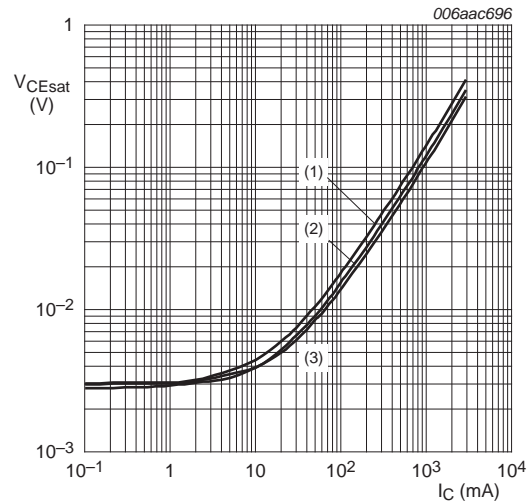
[1] Pulse test: $t_p \leq 300\text{ }\mu\text{s}; \delta \leq 0.02$.





$V_{CE} = 1\text{ V}$
 (1) $T_{amb} = -55\text{ °C}$
 (2) $T_{amb} = 25\text{ °C}$
 (3) $T_{amb} = 100\text{ °C}$

Fig 9. Base-emitter voltage as a function of collector current; typical values



$I_C/I_B = 10$
 (1) $T_{amb} = 100\text{ °C}$
 (2) $T_{amb} = 25\text{ °C}$
 (3) $T_{amb} = -55\text{ °C}$

Fig 10. Collector-emitter saturation voltage as a function of collector current; typical values

8. Test information

8.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - *Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

9. Package outline

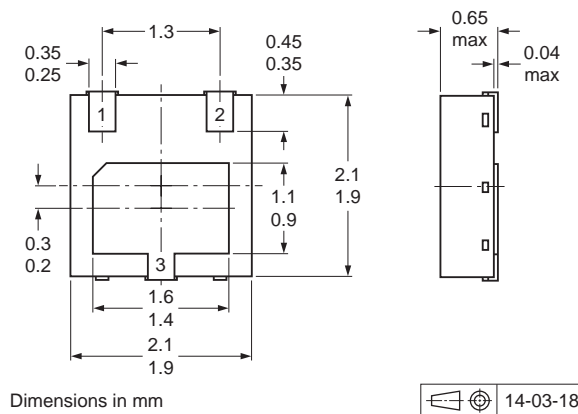


Fig 11. Package outline DFN2020D-3 (SOT1061D)

10. Soldering

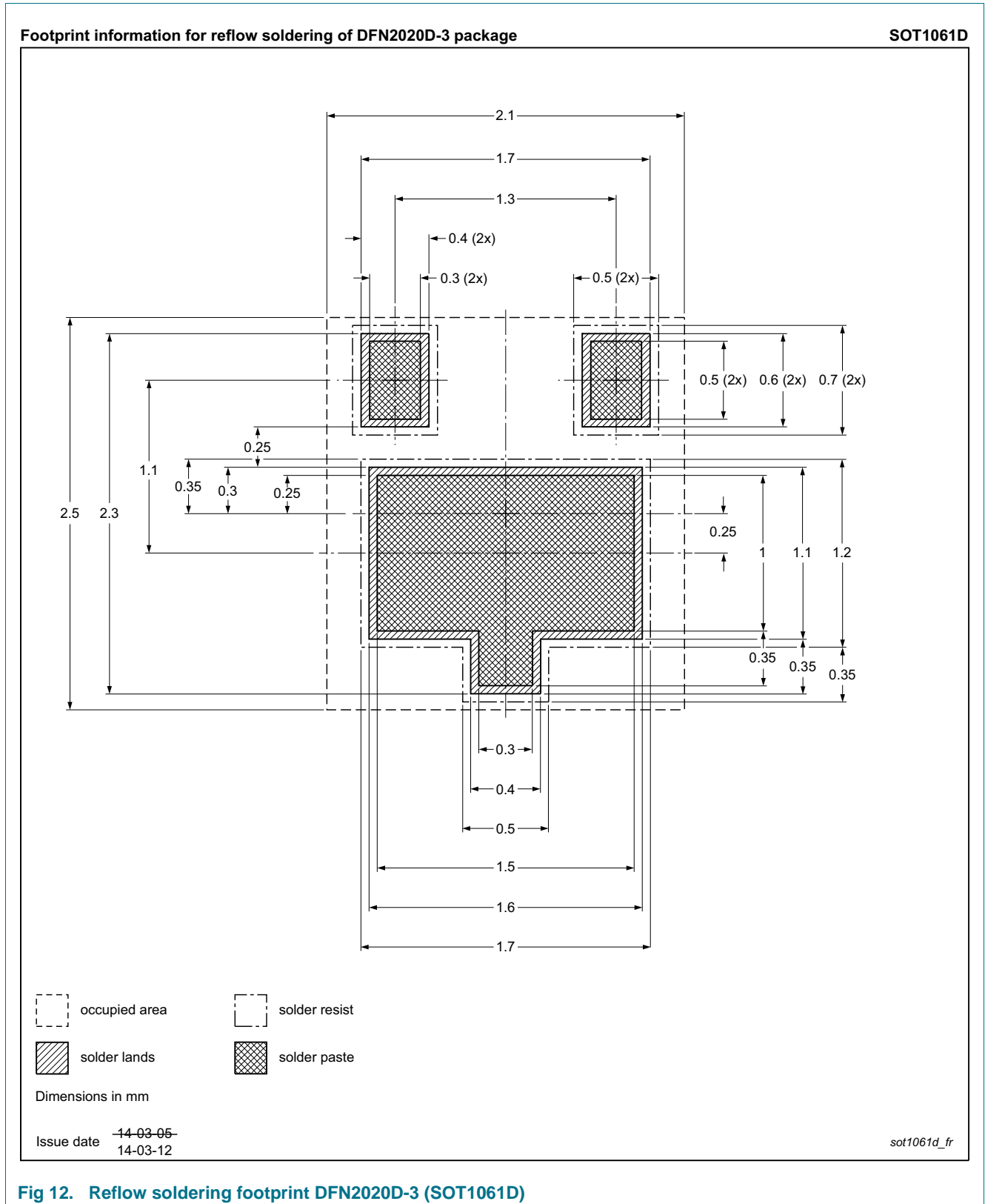


Fig 12. Reflow soldering footprint DFN2020D-3 (SOT1061D)

11. Revision history

Table 8. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BC68PAS_SER v.1	20150619	Product data sheet	-	-

12. Legal information

12.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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[2] The term 'short data sheet' is explained in section "Definitions".

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